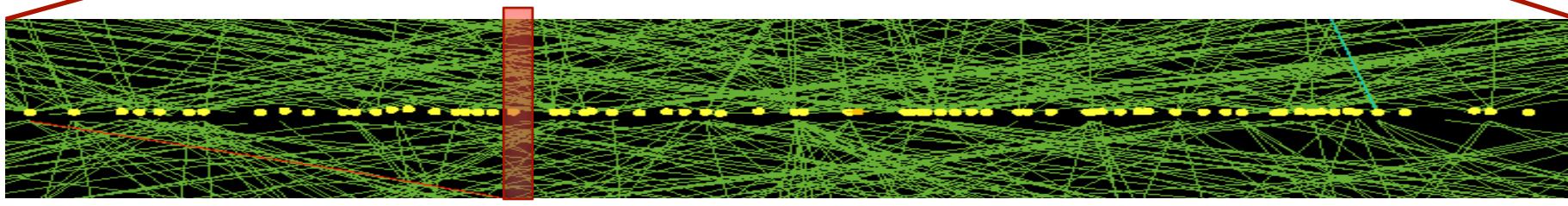
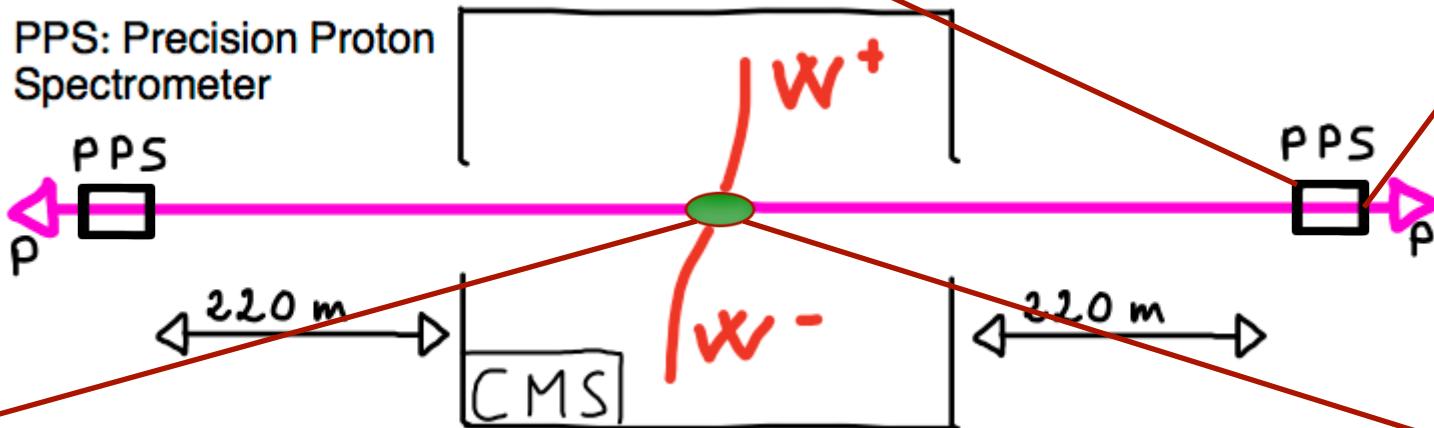
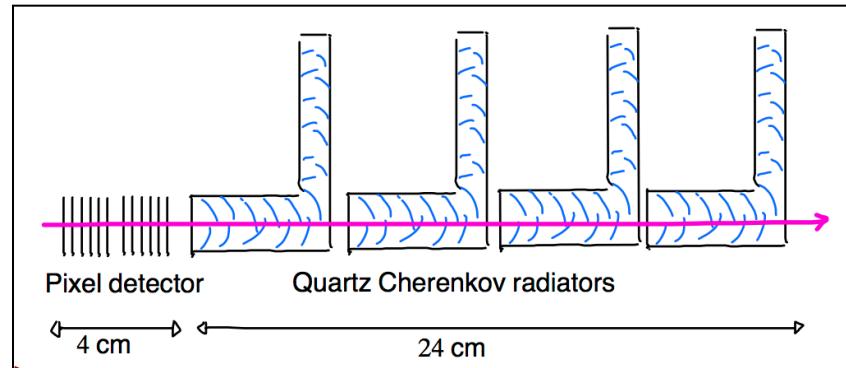


# CMS - TOTEM PPS Detector

## PPS goal:

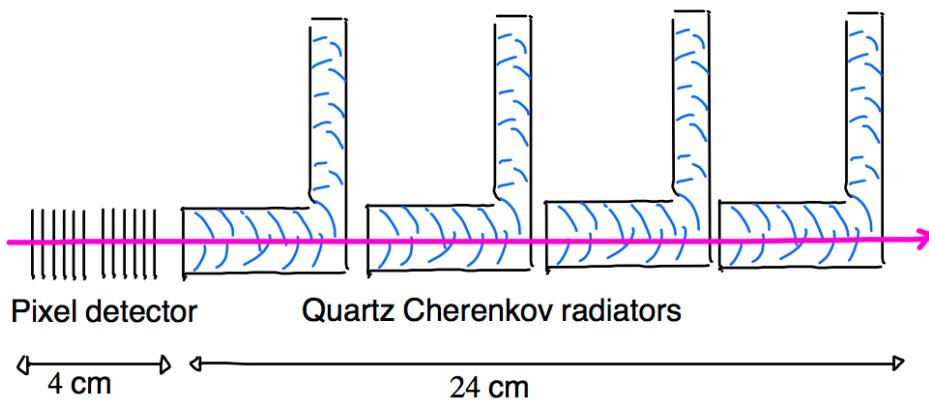
- Position  $\sim 30$  micron
- Timing  $\sim 10$  ps



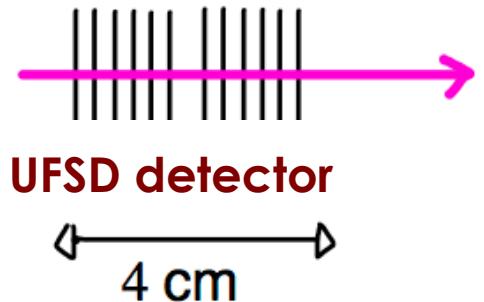
Use z-by-timing to select the right vertex

# Ultra-Fast Silicon Detector

**Pixel + Quartic**



**UFSD:  
one single device**



$$\sigma_T = \frac{30 \text{ ps}}{\sqrt{4}}$$

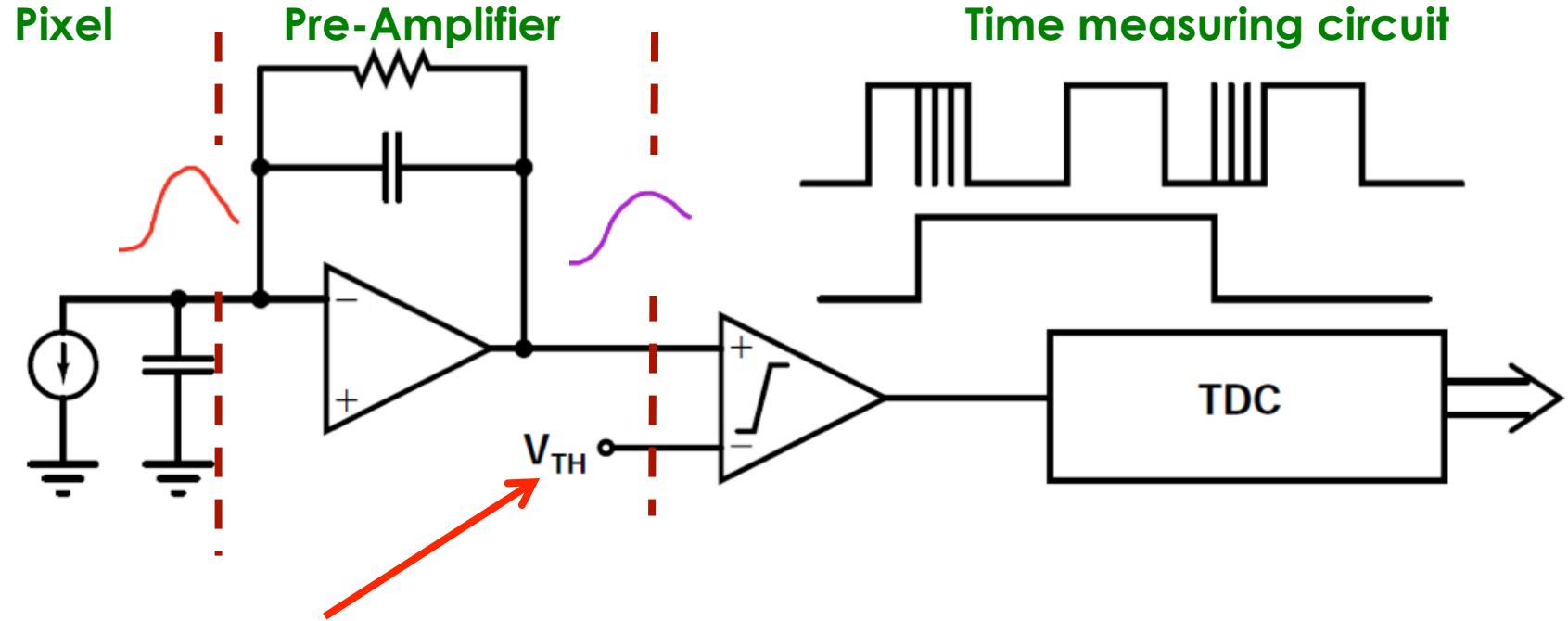
$$\sigma_T = \frac{? \text{ ps}}{\sqrt{12}}$$

# Timing capability of Silicon Detector

**What is the timing precision of Silicon detectors?**

**Can we design a silicon detector precise enough?**

# UFSD: a time-tagging detector



**Time is set when the signal crosses the comparator threshold**

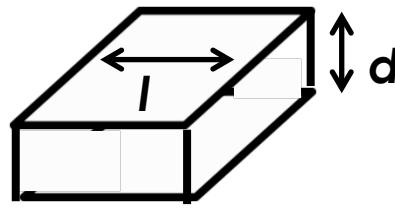
The timing capabilities are determined by the characteristics of the signal at the output of the pre-Amplifier and by the TDC binning:

$$\sigma_{\text{Total}}^2 = \sigma_{\text{Jitter}}^2 + \sigma_{\text{Time Walk}}^2 + \sigma_{\text{TDC}}^2$$

# A parameterization of $\sigma_t$

$$\sigma_t^2 = \left( \frac{t_{rise}}{S/N} \right)^2 + \left( \left[ \frac{t_{rise} V_{th}}{S} \right]_{RMS} \right)^2 + \left( \frac{TDC_{bin}}{\sqrt{12}} \right)^2 \quad (1)$$

Jitter                  Time Walk                  TDC



d: **detector thickness** [micron]

l: **pitch** [micron]

C: **Detector capacitance [fF]**

Depends on the pitch and thickness

N: **Noise at preamp.**

Dominated by the voltage term

S: **Signal**

$$C_{Det} = \epsilon \epsilon_o \frac{l * l}{d} + 0.2 * 4l + 50$$

$$N \propto \frac{C_{Det}}{\sqrt{t_{rise}}}$$

$t_{rise}$ : **Pre-Amp Shaping time**

Use eq. slide (7)

$V_{th}$ : **Comparator threshold**

Depends on the noise level

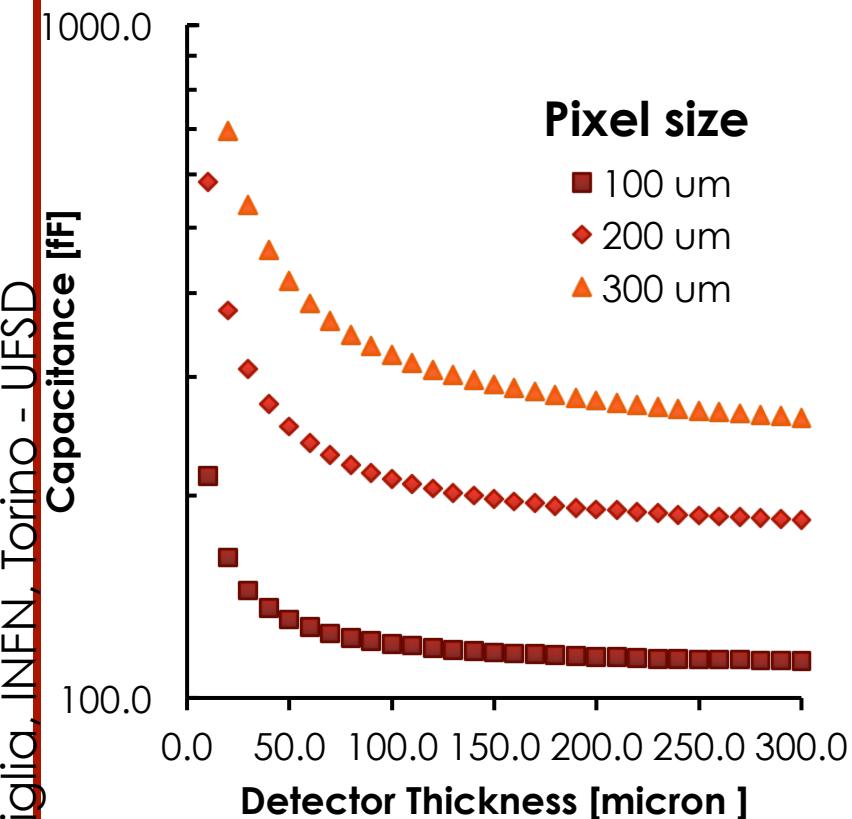
$$V_{th} = 10 * N$$

TDC: **Width of the TDC LSB** [ps]

$$LSB = 20$$

# Values used in the parameterization

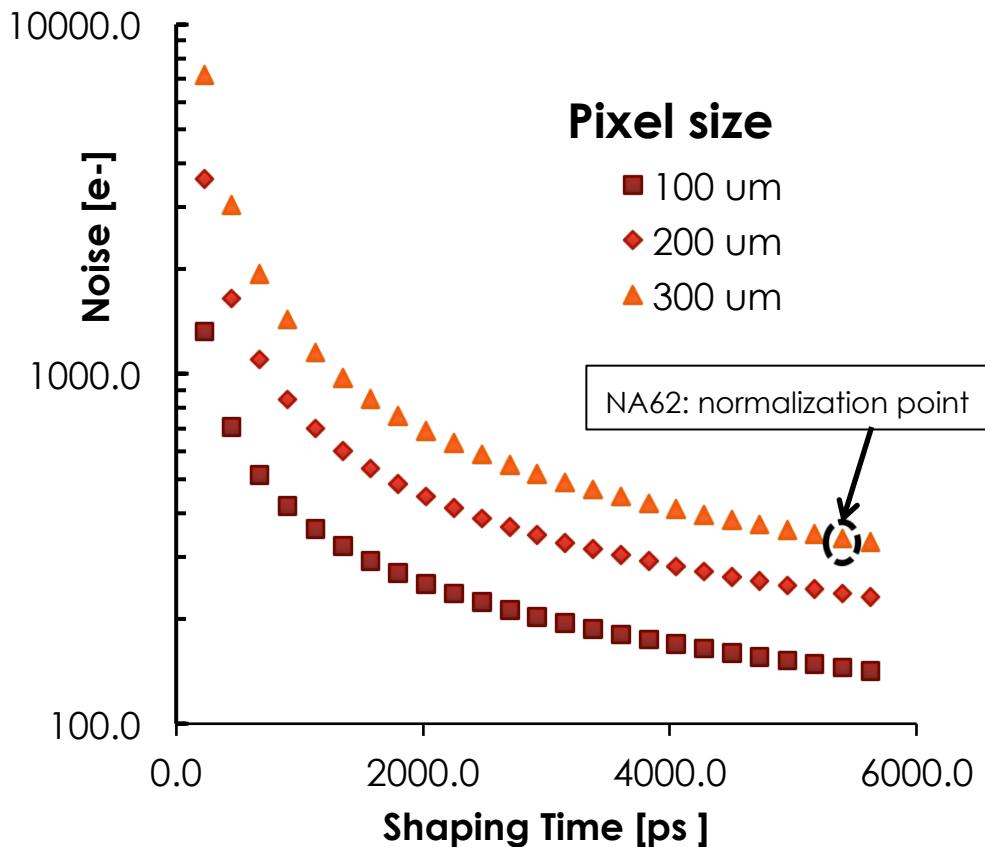
**Capacitance vs Thickness**



## Capacitance:

backplane +  $0.2 \text{ fF}/\mu\text{m}$  (perimeter)  
+ 50 fF (fix term)

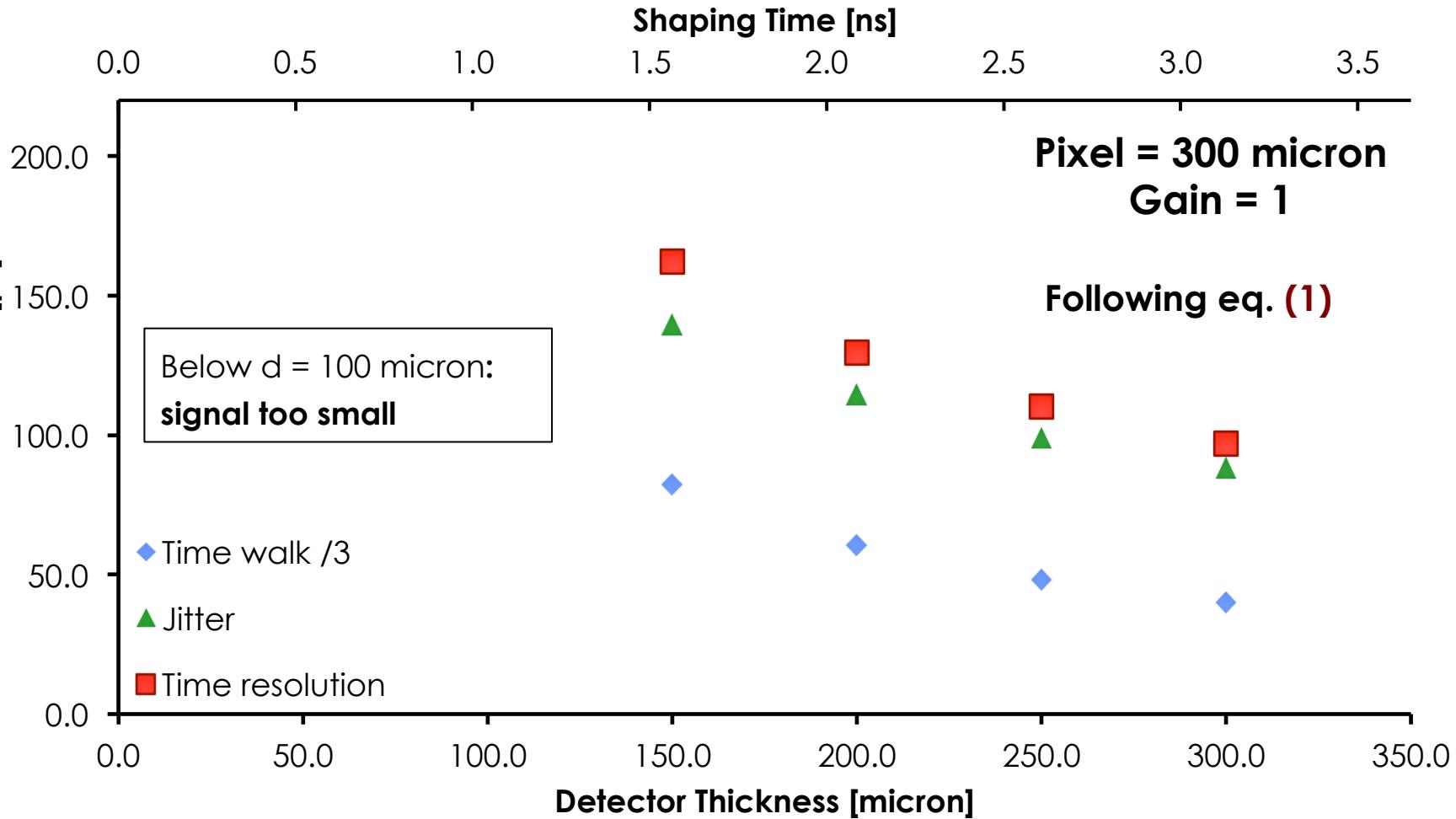
**Noise vs Shaping Time**



## Noise normalized to NA62:

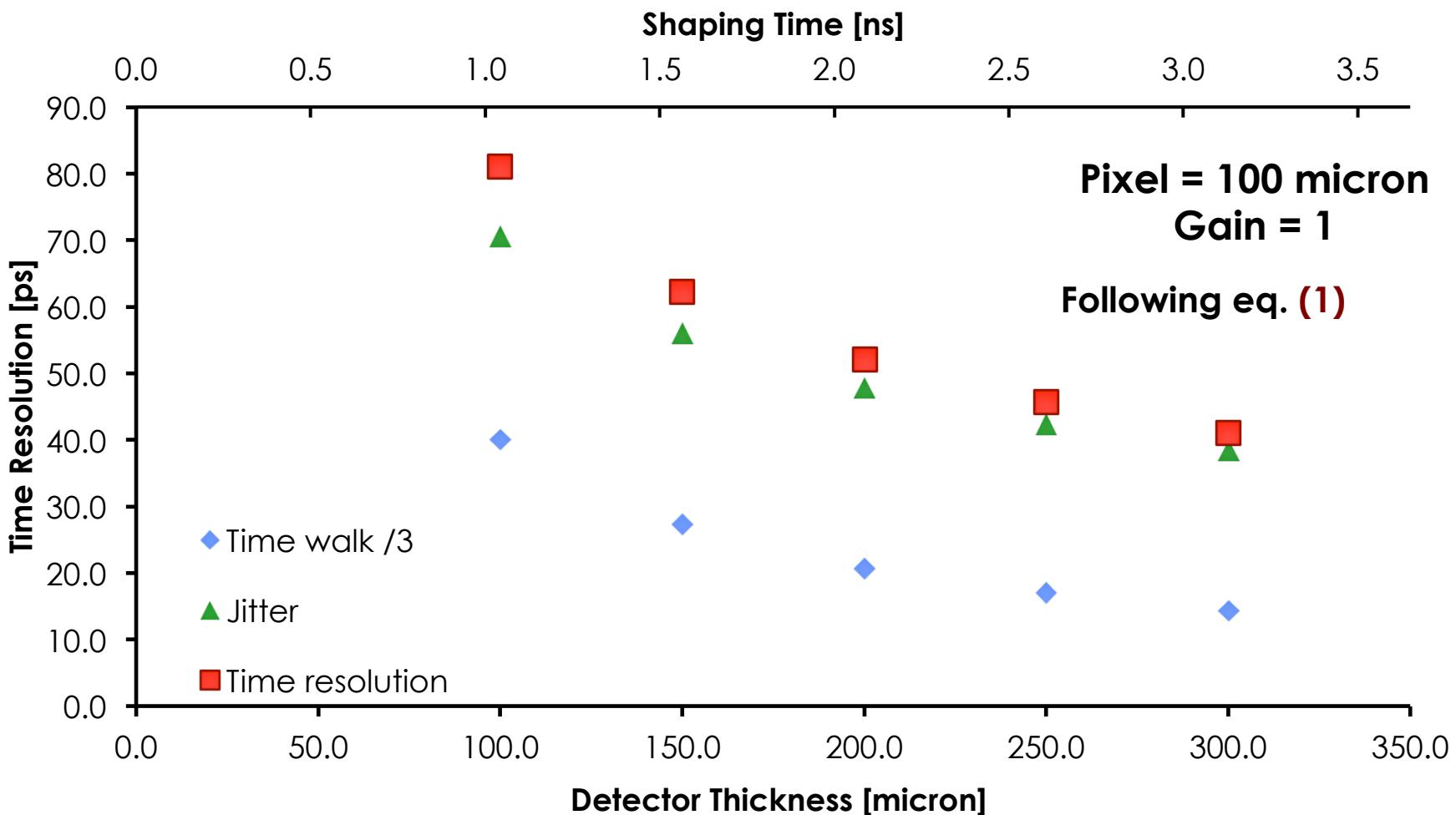
Shaping time  $\sim 5500$  ps,  
noise  $\sim 300$  e-

# State of the Art



**Best resolution achievable:  $\sim 100$  ps**  
(assuming Time Walk reduction of  $\sim 3$ )

# State of the Art



**Best resolution achievable:  $\sim 50$  ps**  
(assuming Time Walk reduction of  $\sim 3$ )

# How can we do better?

$$\sigma_t^2 = \left( \frac{t_{rise}}{S/N} \right)^2 + \left( \left[ \frac{t_{rise} V_{th}}{S} \right]_{RMS} \right)^2 + \left( \frac{TDC_{bin}}{\sqrt{12}} \right)^2$$

Boost the signal: **introduce gain**

$$S \Rightarrow G * S$$

**Impact ionization model:** if the electric field is high enough, the carriers are multiplied according to:

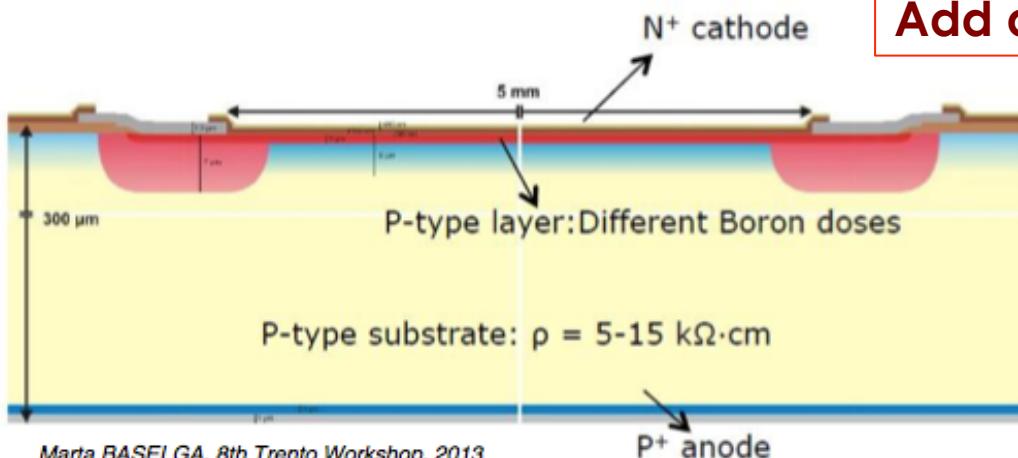
$$N(\ell) = N_0 * e^{(\alpha * \ell)} = G * N_0$$

In Silicon, at 270kV/cm:

- $\alpha_e \approx 0.7$  pair/ $\mu m$
- $\alpha_h \approx 0.1$  pair/ $\mu m$

(see backup slides for details)

# A new design of silicon detector

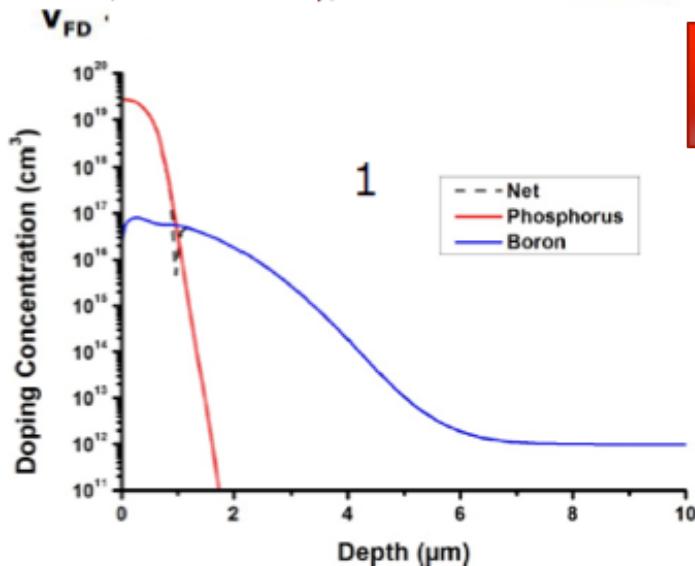


Marta BASELGA, 8th Trento Workshop, 2013

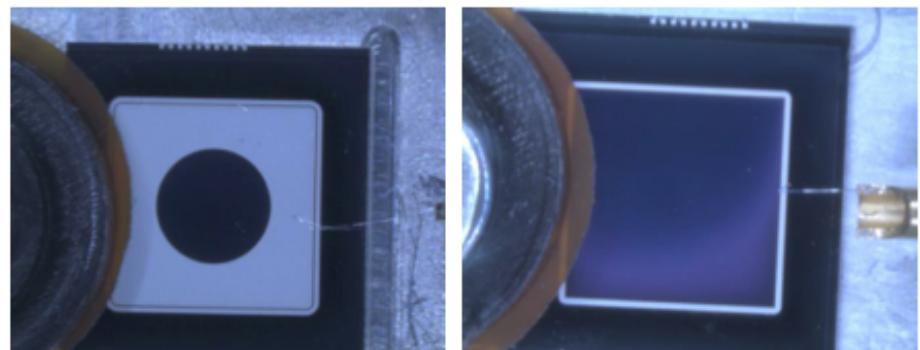
Add a layer of doping to obtain gain

n<sup>++</sup> - p<sup>+</sup> - p - p<sup>+</sup> structure

$10^{16-17} \text{ cm}^{-3}$  – much larger than in the bulk. Large  $N_{\text{eff}}$  provokes avalanche multiplication by impact ionization.

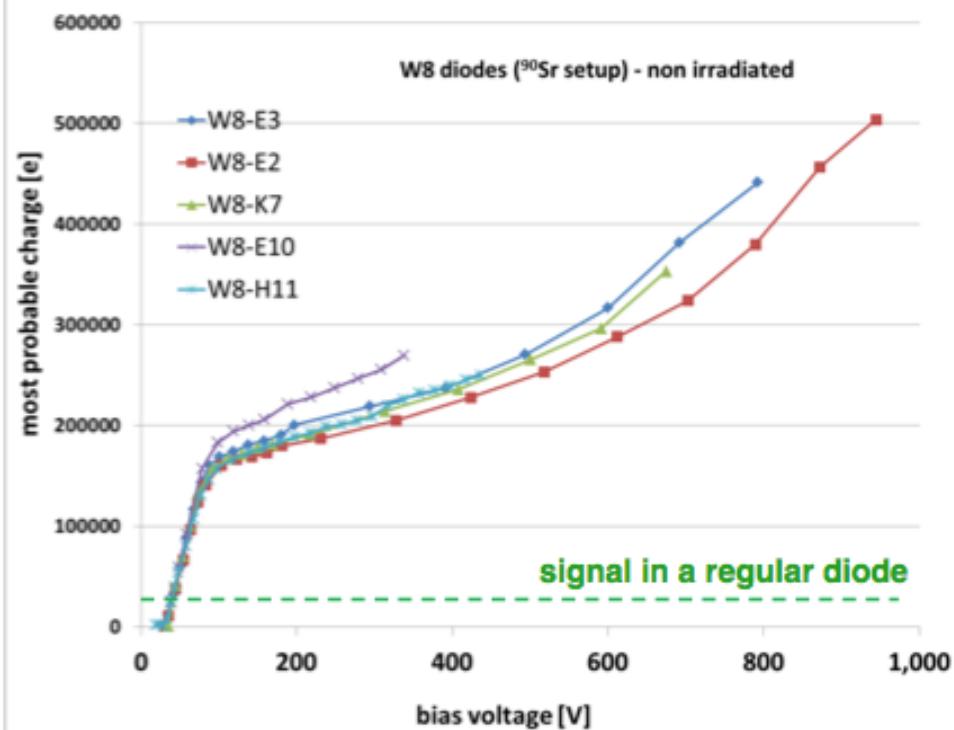
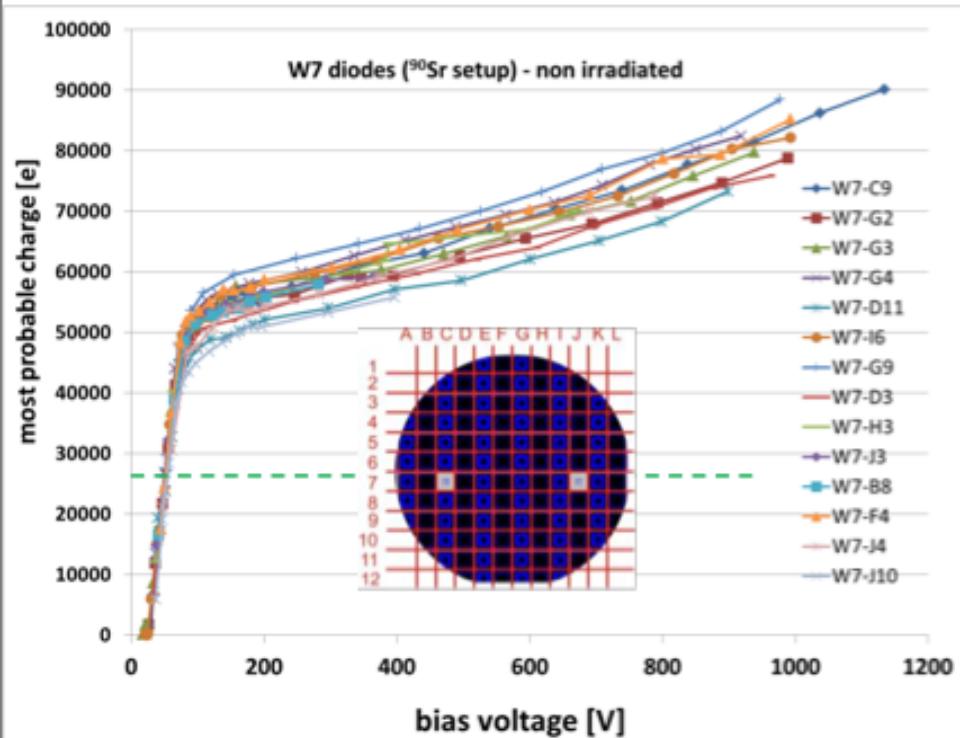


Prototype Detectors exist!

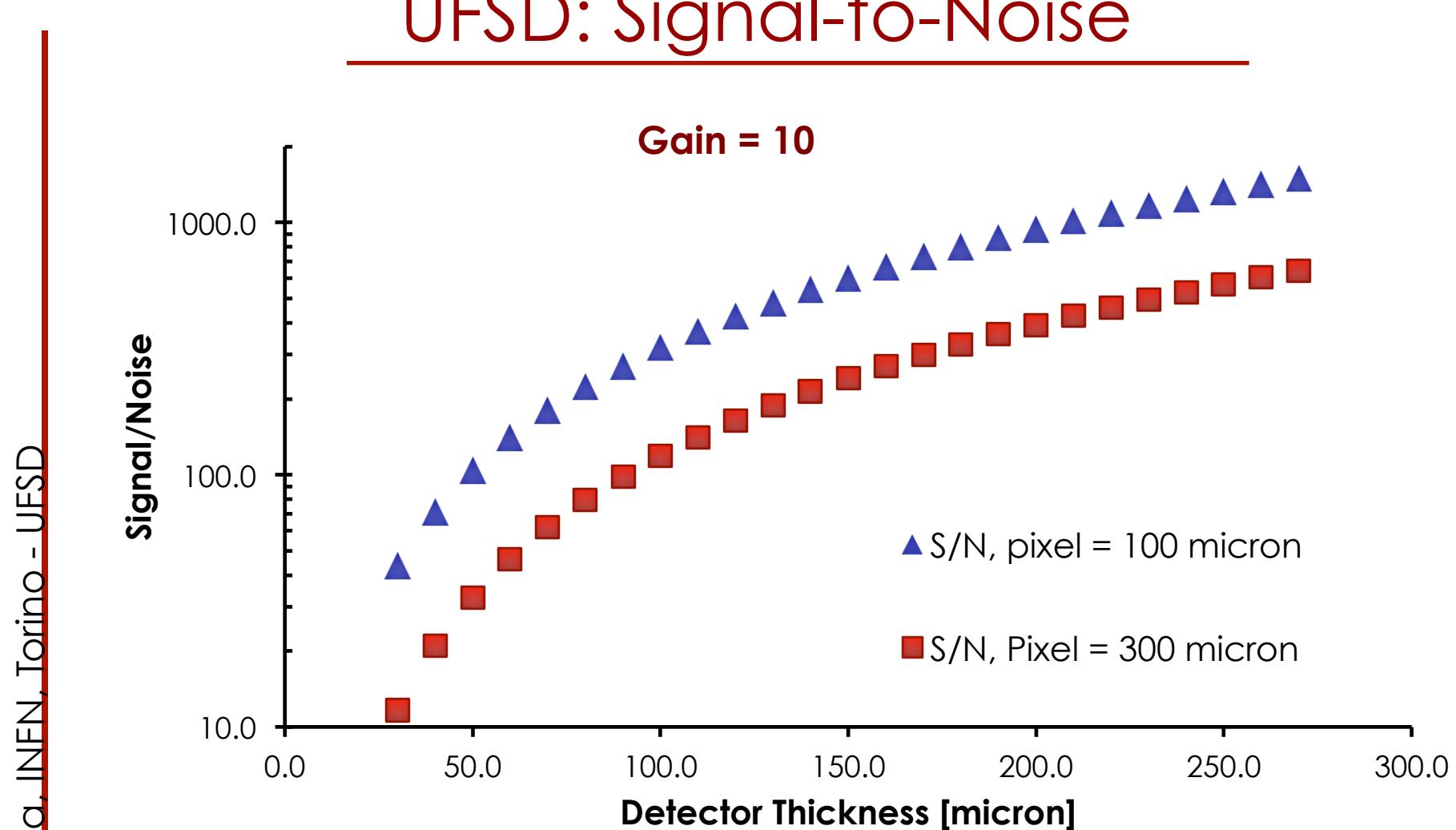


# Results from Ultra – Fast silicon detector

Two sets of detectors, with gain 3 and 10



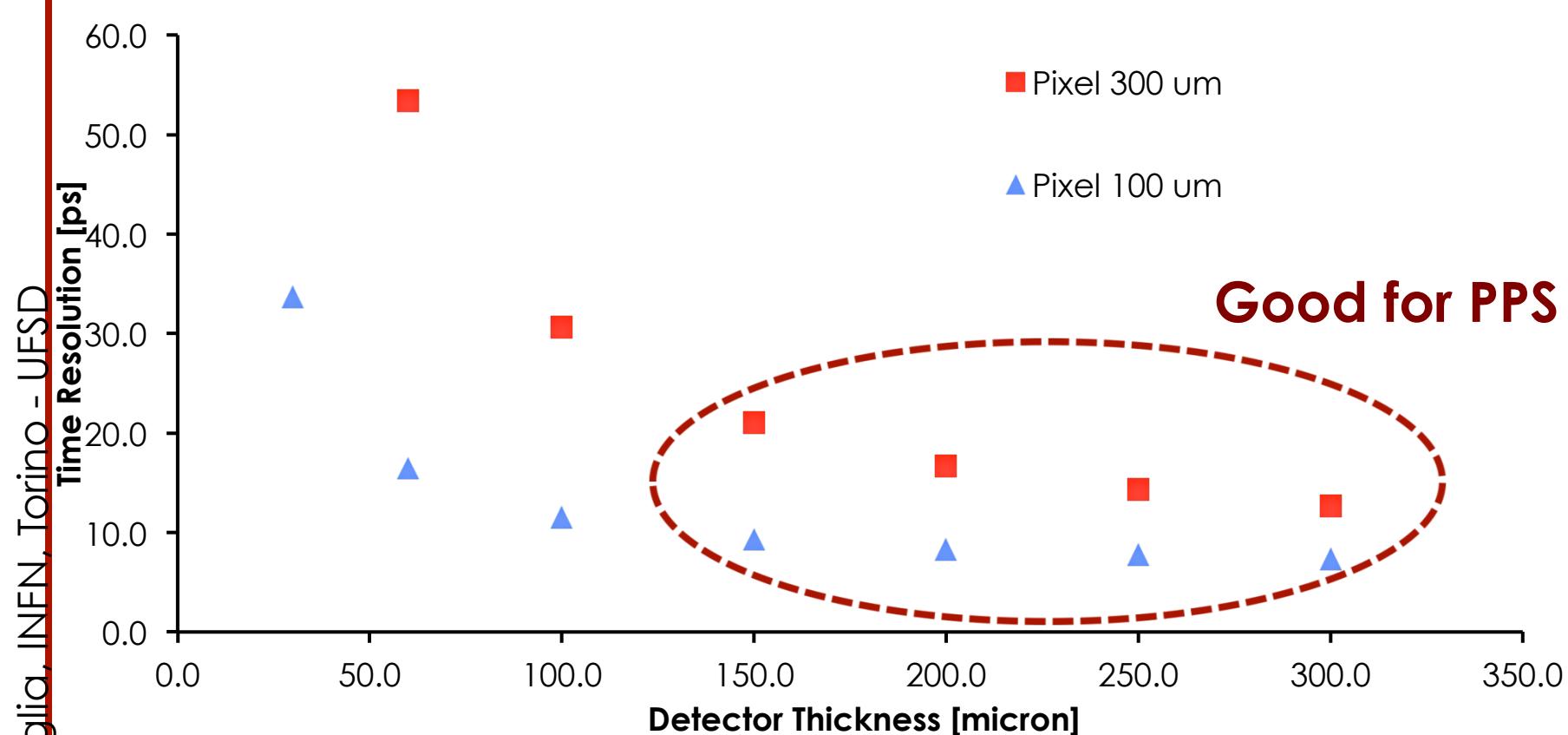
# UFSD: Signal-to-Noise



UFSD offers an excellent S/N ratio even with very thin detectors

# Resolution for 100 and 300 $\mu\text{m}$ pixel

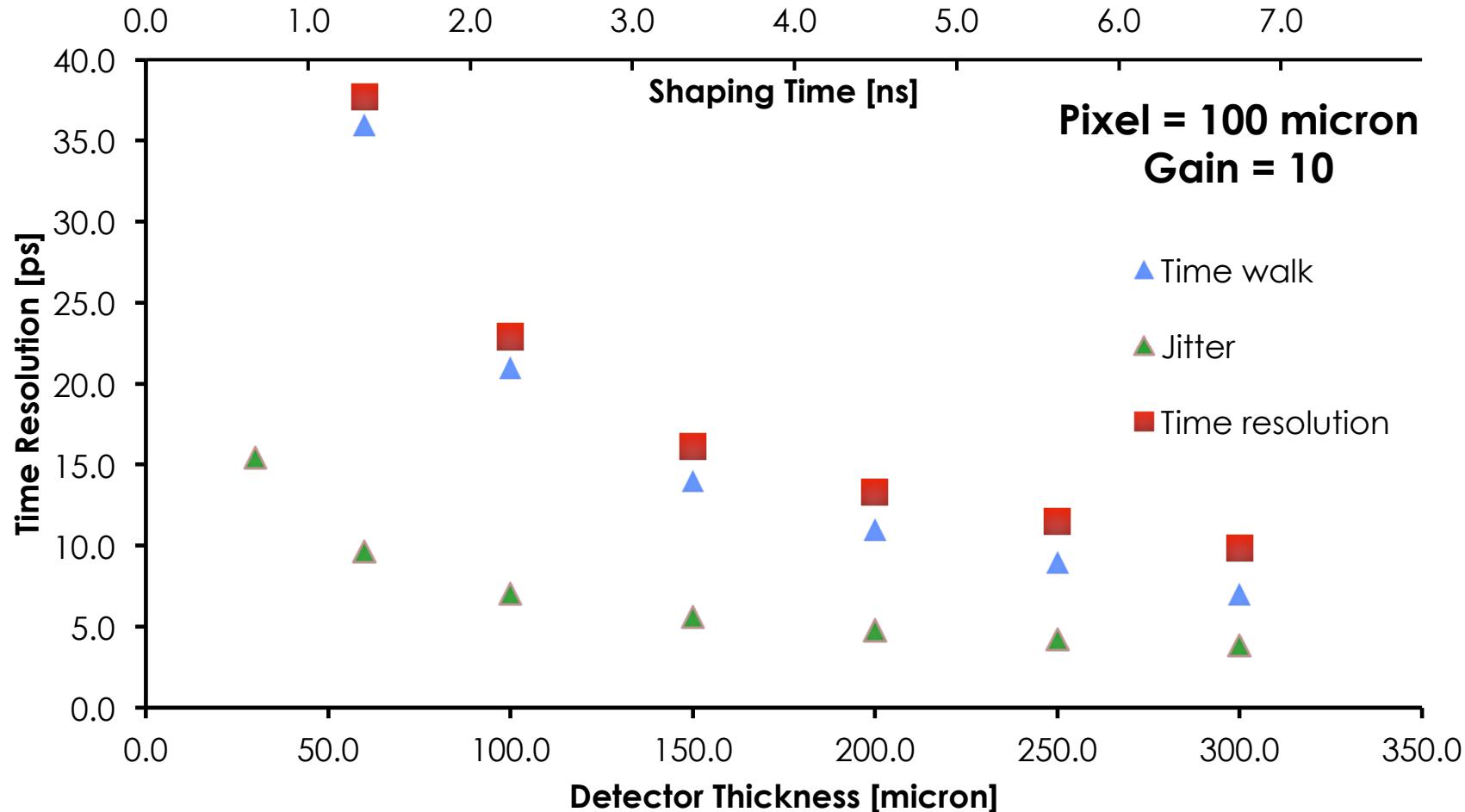
Gain = 10



Good for PPS

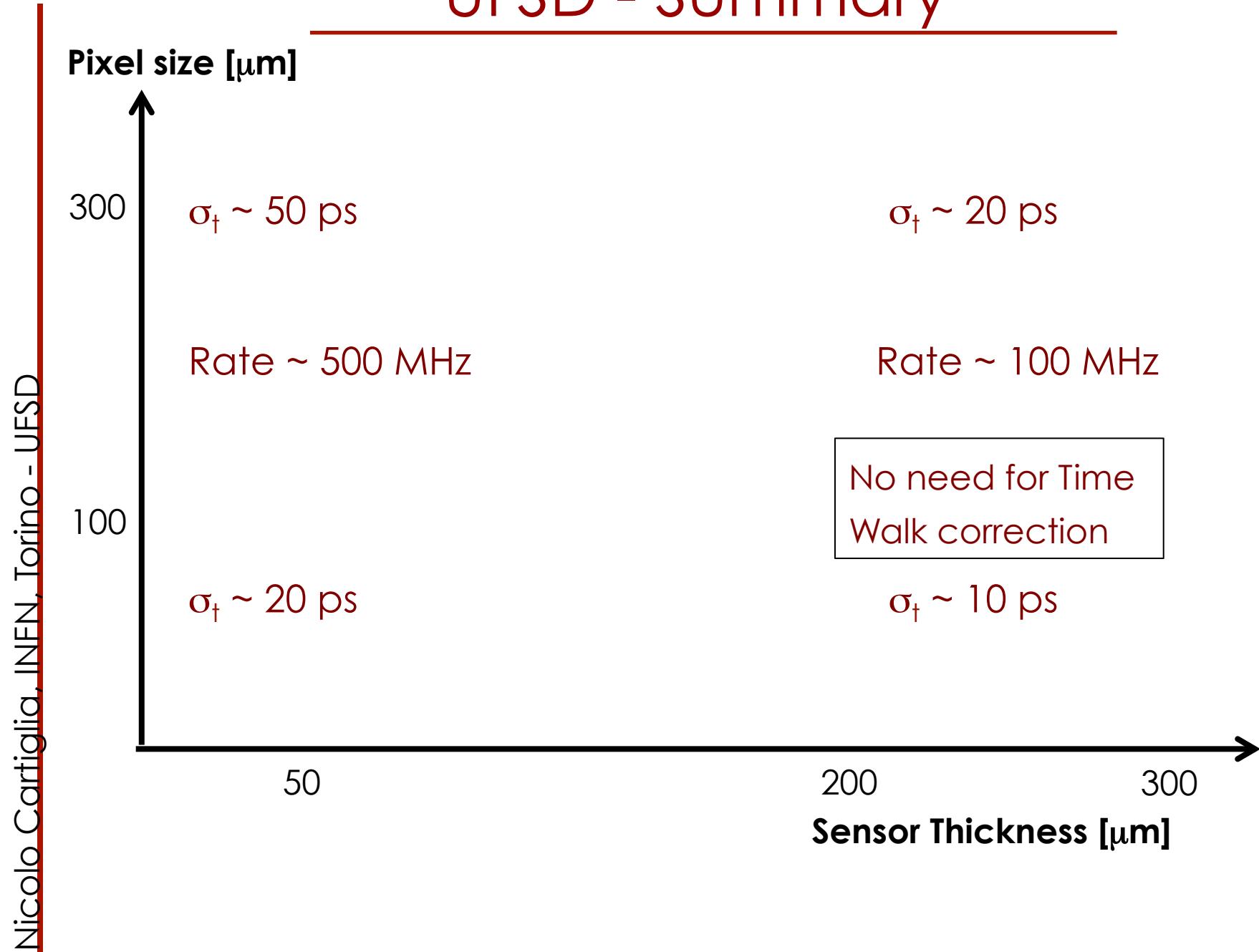
Excellent time resolution requires thicker detectors

# No Time Walk Correction



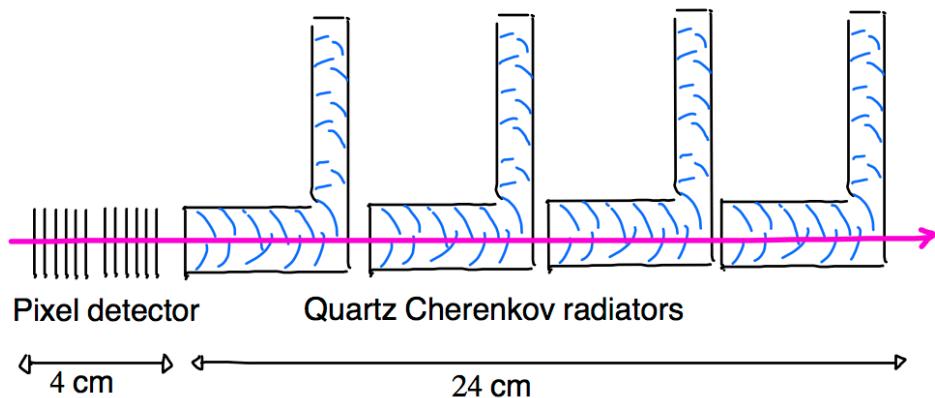
Nicolo Cartiglia, INFN, Torino - UFSD  
Excellent timing resolution even **without Time Walk correction**  
→ Much simpler electronics

# UFSD - Summary

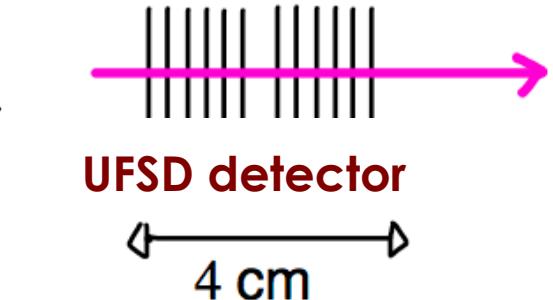
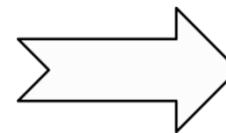


# Conclusion

Pixel + Quartic



UFSD:  
one single device



$$\sigma_T = \frac{30 \text{ ps}}{\sqrt{4}}$$

$$\sigma_T = \frac{20 \text{ ps}}{\sqrt{12}}$$

1. Silicon detector with gain of  $\sim 10$  are well suited for combining excellent position and timing resolution
2. First prototype very promising



**Back - up**

# What is the best shaping time ( $t_{rise}$ ) ?

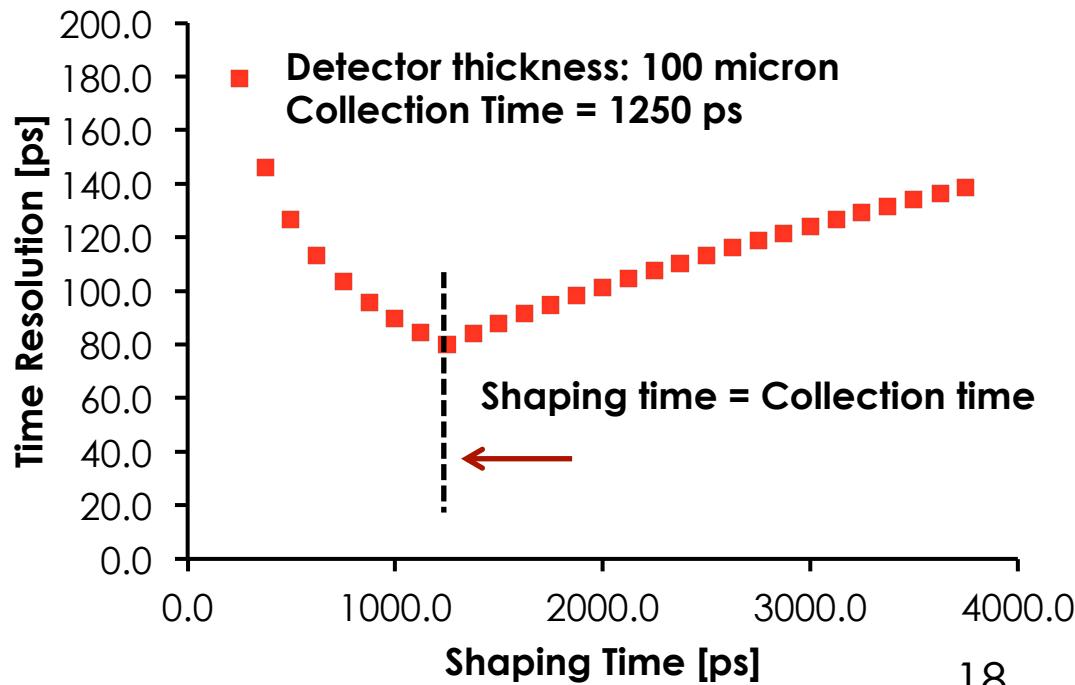
$$N \propto \frac{C_{Det}}{\sqrt{t_{rise}}}$$
$$S \propto \begin{cases} t_{rise} & \xrightarrow{\text{if}} t_{rise} \leq t_{col} \\ Const & \xrightarrow{\text{if}} t_{rise} > t_{col} \end{cases}$$
$$V_{th} \propto N$$

$$\Rightarrow \sigma_t \propto \begin{cases} \frac{C_{det}}{\sqrt{t_{rise}}} & \xrightarrow{\text{if}} t_{rise} \leq t_{col} \\ C_{det} * \sqrt{t_{rise}} & \xrightarrow{\text{if}} t_{rise} > t_{col} \end{cases}$$

To minimize time resolution:

$$t_{rise} \sim t_{col}$$

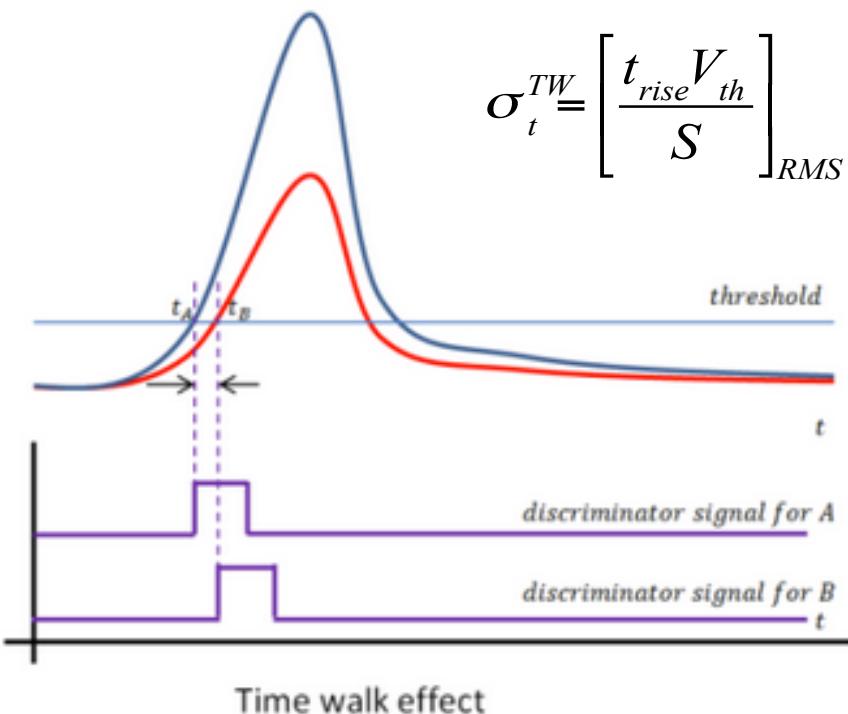
**Note:** This value also minimizes fake signals in neighboring pixels.



# Time walk and Time jitter

**Time walk:** the voltage value  $V_0$  is reached at different time for signal of different amplitudes

$$\sigma_t^{TW} = \left[ \frac{t_{rise} V_{th}}{S} \right]_{RMS}$$

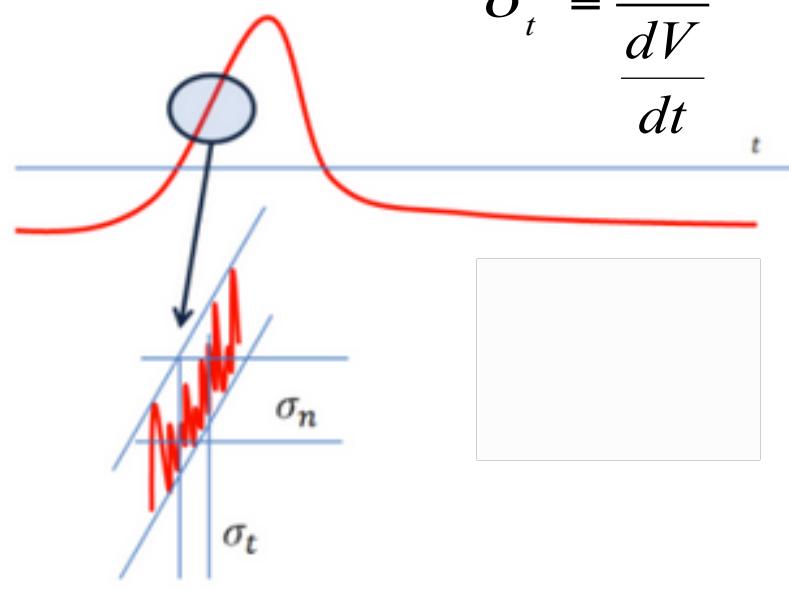


**Due to the physics of signal formation**

(see backup slides for full calculation and reduction techniques)

**Jitter:** the noise is summed to the signal, causing amplitude variations

$$\sigma_t^J = \frac{N}{\frac{dV}{dt}}$$



**Mostly due to electronic noise**

(see backup slides for capacitance and noise values used)